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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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# RClamp0503F RailClamp®

# TVS Array for USB OTG Interfaces

## PROTECTION PRODUCTS - RailClamp®

#### Description

RailClamp® TVS arrays are low capacitance ESD protection devices designed to protect high speed data interfaces.. This series has been specifically designed to protect sensitive components which are connected to data and transmission lines from overvoltage caused by **ESD** (electrostatic discharge), **CDE** (Cable Discharge Events), and **EFT** (electrical fast transients).

The unique design incorporates surge rated, low capacitance steering diodes and a TVS diode in a single package. During transient conditions, the steering diodes direct the transient to either the positive side of the power supply line or to ground. The internal TVS diode prevents over-voltage on the power line, protecting any downstream components.

The low capacitance array configuration allows the user to protect three high-speed data or transmission lines. The low inductance construction minimizes voltage overshoot during high current surges. This device is optimized for ESD protection of USB OTG and SIM interfaces. They may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4 (±15kV air, ±8kV contact discharge).

#### **Features**

- ◆ Transient protection for high-speed data lines to IEC 61000-4-2 (ESD) ±25kV (air), ±20kV (contact) IEC 61000-4-4 (EFT) 40A (5/50ns)
- Array of surge rated diodes with internal TVS Diode
- Small package saves board space
- ◆ Protects three I/O lines & power line
- Low capacitance (<3pF) for high-speed interfaces</li>
- Low clamping voltage
- Low operating voltage: 5.0V
- Solid-state silicon-avalanche technology

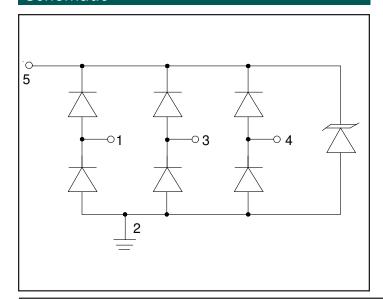
#### Mechanical Characteristics

- ◆ EIAJ SC-70 5L package
- ◆ Molding compound flammability rating: UL 94V-0
- ◆ Lead Finish: Matte Tin
- ◆ Pb-Free, Halogen Free, RoHS/WEEE Compliant
- ♦ Marking: F53
- Packaging : Tape and Reel

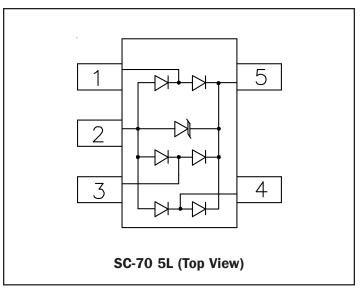
#### **Applications**

- USB OTG interfaces
- SIM Ports
- Video Graphics Cards
- Personal Digital Assistants (PDAs)
- Monitors and Flat Panel Displays
- Portable Electronics
- Microcontroller Input Protection

#### Schematic



## Schematic & PIN Configuration





# **Absolute Maximum Rating**

Rating	Symbol	Value	Units
Peak Pulse Power (tp = 8/20μs)	P <sub>pk</sub>	150	Watts
Maximum Peak Pulse Current (tp = 8/20μs)	I <sub>pp</sub>	6	Amps
ESD per IEC 61000-4-2 (Air) <sup>1</sup> ESD per IEC 61000-4-2 (Contact) <sup>1</sup>	V <sub>ESD</sub>	+/- 25 +/- 20	kV
Operating Temperature	T <sub>J</sub>	-55 to +125	°C
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C

# Electrical Characteristics (T=25°C)

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V <sub>RWM</sub>	Pin 5 to 2			5	V
Reverse Breakdown Voltage	V <sub>BR</sub>	I <sub>t</sub> = 1mA Pin 5 to 2	6			V
Reverse Leakage Current	I <sub>R</sub>	V <sub>RWM</sub> = 5V, T=25°C Pin 5 to 2			3	μΑ
Clamping Voltage	V <sub>c</sub>	I <sub>pp</sub> = 1A, tp = 8/20μs Pin 1, 3, or 4 to Pin 2			15	V
Clamping Voltage	V <sub>c</sub>	I <sub>pp</sub> = 6A, tp = 8/20μs Pin 1, 3, or 4 to Pin 2			25	V
Junction Capacitance	C <sub>j</sub>	V <sub>R</sub> = 0V, f = 1MHz Pin 1, 3, or 4 to Pin 2			3	pF
		V <sub>R</sub> = 0V, f = 1MHz Between any two I/O pins (1, 3, 4)			1.5	pF

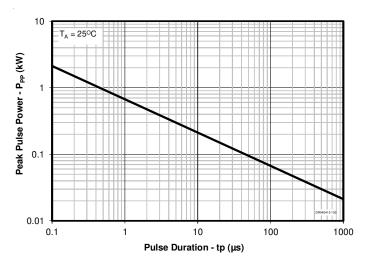
Notes

1)ESD gun return path connected to ESD ground reference plane.

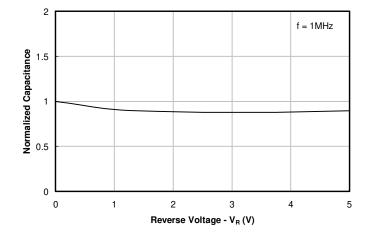


### Typical Characteristics

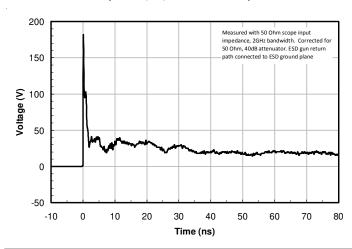
#### Non-Repetitive Peak Pulse Power vs. Pulse Time



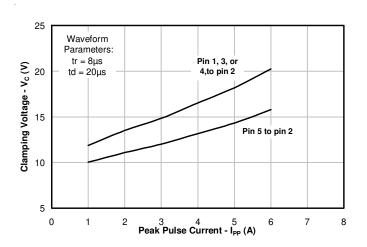
Junction Capacitance vs. Reverse Voltage (Pin 1, 3, or 4 to GND - Normalized to 0V)



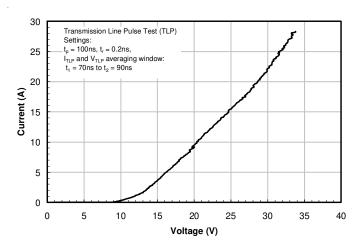
#### ESD Clamping (+8kV Contact per IEC 61000-4-2) (Pin 1, 3, or 4 to GND)



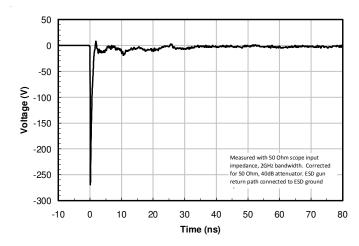
#### Clamping Voltage vs. Peak Pulse Current (tp=8/20us)



TLP Characteristic (Pin 1, 3, or 4 to GND)

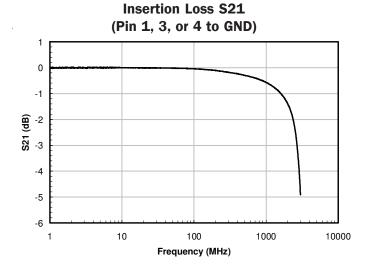


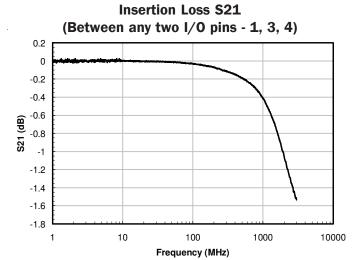
# ESD Clamping (-8kV Contact per IEC 61000-4-2) (Pin 1, 3, or 4 to GND)





# Typical Characteristics





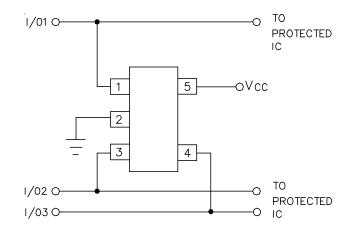


#### **Applications Information**

# **Device Connection Options for Protection of Three High-Speed Data Lines**

This device is designed to protect three data lines from transient over-voltages by clamping them to a fixed reference. When the voltage on the protected line exceeds the reference voltage (plus diode  $V_{\rm F}$ ) the steering diodes are forward biased, conducting the transient current away from the sensitive circuitry. Data lines are connected at pins 1, 3, and 4. The negative reference is connected at pin 2. This pin should be connected directly to a ground plane on the board for best results. The path length is kept as short as possible to minimize parasitic inductance. Connect pin 5 directly to the positive supply rail ( $V_{\rm cc}$ ). In this configuration the data lines are referenced to the supply voltage. The internal TVS diode prevents over-voltage on the supply rail.

# Data Line and Power Supply Protection Using Vcc as reference

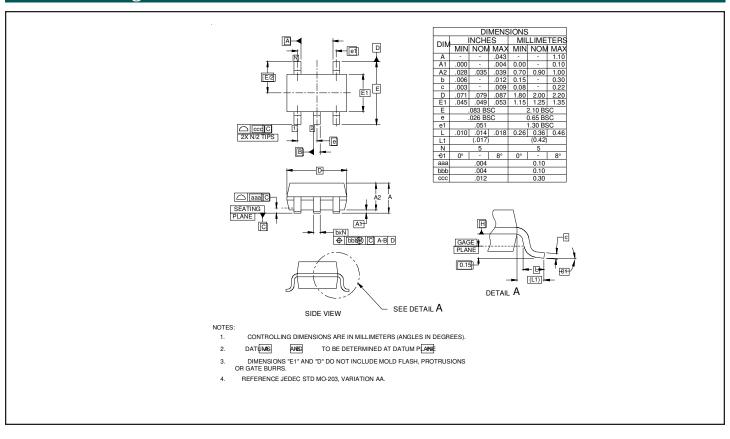


#### **Matte Tin Lead Finish**

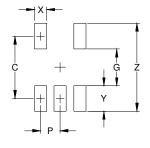
Matte tin has become the industry standard lead-free replacement for SnPb lead finishes. A matte tin finish is composed of 100% tin solder with large grains. Since the solder volume on the leads is small compared to the solder paste volume that is placed on the land pattern of the PCB, the reflow profile will be determined by the requirements of the solder paste. Therefore, these devices are compatible with both lead-free and SnPb assembly techniques. In addition, unlike other lead-free compositions, matte tin does not have any added alloys that can cause degradation of the solder joint.



# Outline Drawing - SC-70 5L



## Land Pattern - SC-70 5L



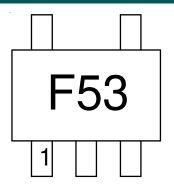
DIMENSIONS							
DIM	M INCHES MILLIMETER						
С	(.073)	(1.85)					
G	.039	1.00					
Ρ	.026	0.65					
Χ	.016	0.40					
Υ	.033	0.85					
Z	.106	2.70					

#### NOTES:

THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY.
CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR
COMPANY'S MANUFACTURING GUIDELINES ARE MET.



## Marking Code

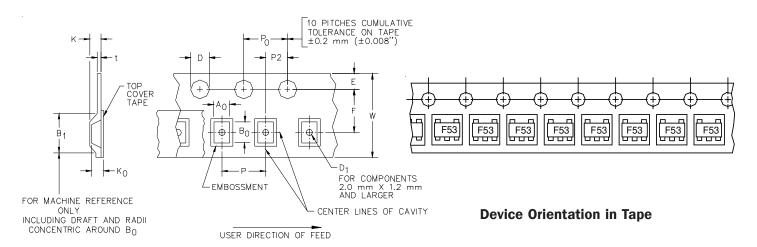


# Ordering Information

Part Number	Lead Finish	Qty per Reel	Reel Size	
RClamp0503F.TCT	Matte Tin	3,000	7 Inch	

RailClamp and RClamp are trademarks of Semtech Corporation.

## Carrier Tape Specification



Tape Width	B, (Max)	D	D1 (MIN)	E	F	K (MAX)	Р	PO	P2	T(MAX)	W
8 mm	4.2 mm (.165)	1.5 + 0.1 mm - 0.0 mm (0.59 +.005 000)	1.0 mm (.039)	1.750±.10 mm (.069±.004)	3.5±0.05 mm (.138±.002)	2.4 mm (.094)	4.0±0.1 mm (.157±.00- 4)	4.0±0.1 mm (.157±.00- 4)	2.0±0.05m- m (.079±.002)	0.4 mm (.016)	8.3 mm (.312±.012)

## Contact Information

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